#### SN54ALS09, SN74ALS09 QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS SDAS084B – APRIL 1982 – REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

These devices contain four independent 2-input positive-AND gates. They perform the Boolean functions  $Y = A \cdot B$  or  $Y = \overline{A} + \overline{B}$  in positive logic. The open-collector outputs require pullup resistors to perform correctly. These outputs may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher V<sub>OH</sub> levels.

The SN54ALS09 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74ALS09 is characterized for operation from 0°C to 70°C.

 FUNCTION TABLE (each gate)

 INPUTS
 OUTPUT

 A
 B
 Y

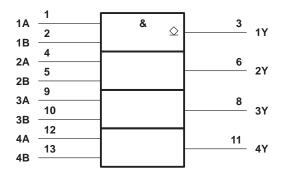
 H
 H
 H

 L
 X
 L

L

L

#### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

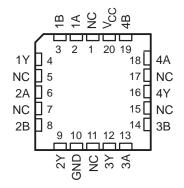
Pin numbers shown are for the D, J, and N packages.

Х

SN54ALS09 . . . J PACKAGE SN74ALS09 . . . D OR N PACKAGE (TOP VIEW)

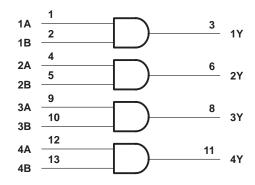
	(10		-**)		
1A 1B 1Y 2A 2B 2Y GND	2 3 4 5 6	σ		V <sub>C</sub> 4B 4A 4Y 3B 3A 3Y	С

SN54ALS09 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### logic diagram (positive logic)



### SN54ALS09, SN74ALS09 QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS

SDAS084B - APRIL 1982 - REVISED DECEMBER 1994

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>	
Off-state output voltage	
Operating free-air temperature range, T <sub>A</sub> : SN54ALS09	
SN74ALS09	0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN	154ALSC	)9	SN74ALS09				
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
VOH	High-level output voltage			5.5			5.5	V	
IOL	Low-level output current			4			8	mA	
ТА	Operating free-air temperature	-55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	ТЕ	SN	154ALSC	)9	SN74ALS09			UNIT	
PARAMETER		ST CONDITIONS	MIN	typ‡	MAX	MIN	typ‡	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	Ij = -18 mA			-1.5			-1.5	V
Vol	V <sub>CC</sub> = 4.5 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.5 V	I <sub>OL</sub> = 8 mA					0.35	0.5	v
lį	V <sub>CC</sub> = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
Iн	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μA
١ <sub>١L</sub>	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0.4 V$			-0.1			-0.1	mA
ЮН	V <sub>CC</sub> = 4.5 V,	V <sub>OH</sub> = 5.5 V			0.1			0.1	mA
Іссн	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 4.5 V		1.35	2.4		1.35	2.4	mA
ICCL	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0$		2.2	4		2.2	4	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

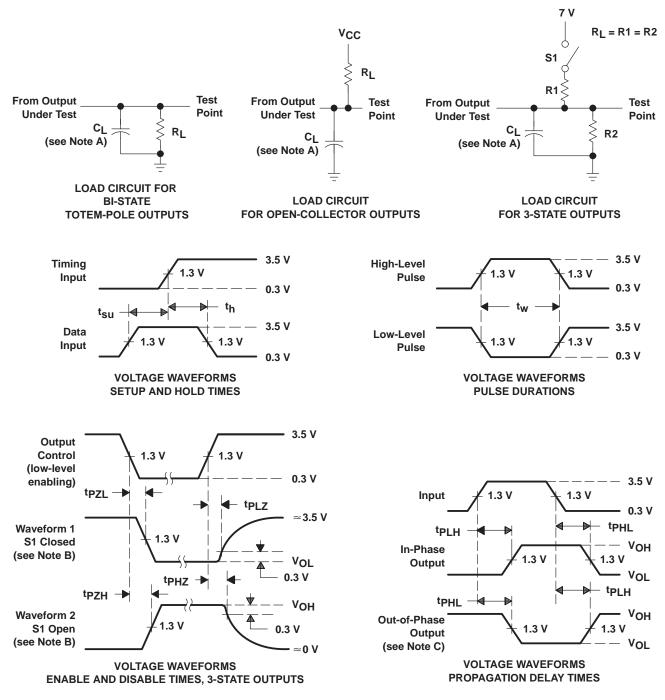
PARAMETER	FROM (INPUT)	то (OUTPUT)	C <sub>L</sub> = 50 p R <sub>L</sub> = 2 ks T <sub>A</sub> = MIN		, to MAX§		UNIT
			SN54A	LS09	SN74A	LS09	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	V	20	69	23	54	
<sup>t</sup> PHL	AUB	T	5	23	5	15	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



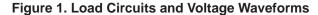
SN54ALS09, SN74ALS09 QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS SDAS084B - APRIL 1982 - REVISED DECEMBER 1994

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz, t<sub>r</sub> = t<sub>f</sub> = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.







#### **PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
84142012A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84142012A SNJ54ALS 09FK
8414201CA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8414201CA SNJ54ALS09J
SN54ALS09J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54ALS09J
SN54ALS09J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54ALS09J
SN74ALS09D	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	ALS09
SN74ALS09DR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS09
SN74ALS09DR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS09
SN74ALS09DR.B	Active	Production	SOIC (D)   14	2500   LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS09
SN74ALS09N	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS09N
SN74ALS09N.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS09N
SNJ54ALS09FK	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84142012A SNJ54ALS 09FK
SNJ54ALS09FK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84142012A SNJ54ALS 09FK
SNJ54ALS09J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8414201CA SNJ54ALS09J
SNJ54ALS09J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8414201CA SNJ54ALS09J

<sup>(1)</sup> **Status:** For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.



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### PACKAGE OPTION ADDENDUM

24-Jul-2025

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS09, SN74ALS09 :

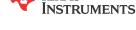
Catalog : SN74ALS09

Military : SN54ALS09

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications



Texas

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#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS09DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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### PACKAGE MATERIALS INFORMATION

23-Jul-2025



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS09DR	SOIC	D	14	2500	353.0	353.0	32.0

#### TEXAS INSTRUMENTS

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### TUBE



### - B - Alignment groove width

#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
84142012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74ALS09N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ALS09N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ALS09N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74ALS09N.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54ALS09FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS09FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

## **D0014A**



## **PACKAGE OUTLINE**

### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



## D0014A

## **EXAMPLE BOARD LAYOUT**

### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



### D0014A

## **EXAMPLE STENCIL DESIGN**

### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### FK 20

### 8.89 x 8.89, 1.27 mm pitch

### **GENERIC PACKAGE VIEW**

### LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





### **GENERIC PACKAGE VIEW**

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



## J0014A



### **PACKAGE OUTLINE**

### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



### J0014A

## **EXAMPLE BOARD LAYOUT**

### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





### N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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